

Automatic Feeding BGA Rework Station WDS 850 AC 220V Mobile Phone Repair

Basic Information

Place of Origin: China
Brand Name: WDS
Certification: CE
Model Number: WDS-850
Minimum Order Quantity: 1 UNIT

Packaging Details: Wooden caseDelivery Time: 8-15 working days

Payment Terms: T/T, Western Union, MoneyGram

• Supply Ability: 150 UNITS PER MONTH



Product Specification

Warranty: 1 YearWeight: 200KGVoltage: AC 220VCurrent: 50/60hz

• Dimensions: L970*W7000*H830mm

• Total Power: 8400W

PCB Size: Max680*550mm Min 10*10 Mm
 BGA Chip Size: Max120*120mm Min 0.8*0.8mm

• Power: Ac220v ±10%,50/60hz

• Heater Power: Upper Temp.one 1600w,second

Temp.zone1600w,IR Temp.zone 5000w

Alignment System: Optical Prism + HD Camera

Highlight: Automatic Feeding BGA Rework Station,

8400W BGA Rework Station, 8400W Reballing Station BGA



More Images







Product Description

HD display Vacuum adsorption WDS-850 Optical alignment automatic repair equipment

Excellent performance features

Multi-language menu interface

Automatic feeding decive

X/Y axis can be controlled by rocker, fast oeration

Imported high-definition CCD(2 million pixels) optical alignment ststem

High precision temperature control system, accurate temperature control system, accuate temperature control

WDS-850



| Power | AC 220V±10 50Hz | Total power | 7600W |
|--------------------|------------------|------------------|-----------------------|
| Up heater power | Max 1200W | Mount max load | 800G |
| Down heater power | Max1200W | IR power | 5000W (2000Wntrolled) |
| Max PCB size | 630*480mm | Min PCB size | 10×10mm |
| Chip magnification | 2-50 multiple | Temp. interface | 5个 |
| Suit PCB thickness | 0.5-8mm | Mount accuracy | ±0.01mm |
| Suit chip size | 0.8*0.8~80*80mm | Chip min spacing | 0.15mm |
| Dimensions | L970*W700*H830mm | Weight | About 210KG |

HD display Vacuum adsorption WDS-850 Optical alignment automatic repair equipment

Excellent performance features

Multi-language menu interface

Automatic feeding decive

X/Y axis can be controlled by rocker, fast oeration

Imported high-definition CCD(2 million pixels) optical alignment ststem

High precision temperature control system, accurate temperature control system, accurate temperature control



HD optical alignment and intelligent control

The integrated design of hot air head and mounting head has the functions of automatic mounting, automatic welding and automatic disassembly. High precision K-type thermocouple (KSENSOR) cLOSED Loop control, up and down independent temperature measurement, temperature control accuracy up to \pm 1 degree, Over-temperature protection alarm function, software encryption and anti-stay function.



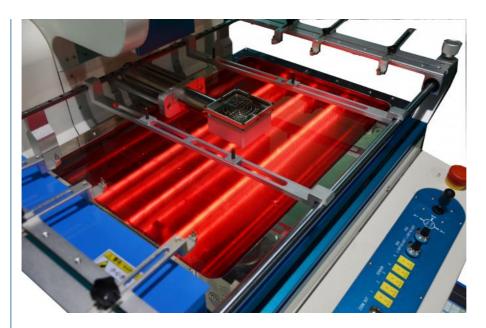
HD display

High-definition imported CCD(2 million pixels) digital imaging, automatic optical zoom system, automatic precision alignment control system with laser red dot, using 15 inch high-definition industrial display screen dispaly.



Vacuum adsorption and preheating platform

The upper heating head is equipped with a vacuum suction pipe for chip adsorption. The bottom preheating platform adopts imported excellent heating materials(infrared gold-plated light tube)+anti-flash thermostatic glass (temperature resistance up to 1800°C). The preheating area is up to 500*420mm. The preheating platform, splint device and cooling system can be moved as a whole in the X direction. Make PCB positioning and folding welding more safe and convenient.



HD optical alignment and intelligent control

The integrated design of hot air head and mounting head has the functions of automatic mounting, automatic welding and automatic disassembly. High precision K-type thermocouple (KSENSOR) cLOSED Loop control, up and down independent temperature measurement, temperature control accuracy up to \pm 1 degree, Over-temperature protection alarm function, software encryption and anti-stay function.



HD display

High-definition imported CCD(2 million pixels) digital imaging, automatic optical zoom system, automatic precision alignment control system with laser red dot, using 15 inch high-definition industrial display screen dispaly.

Vacuum adsorption and preheating platform

The upper heating head is equipped with a vacuum suction pipe for chip adsorption. The bottom preheating platform adopts imported excellent heating materials(infrared gold-plated light tube)+anti-flash thermostatic glass (temperature resistance up to 1800°C). The preheating area is up to 500*420mm. The preheating platform, splint device and cooling system can be moved as a whole in the X direction. Make PCB positioning and folding welding more safe and convenient.

Specification

| Model | WDS-850 | |
|----------------------------------|-------------------------|--|
| Total power supply | 8400W | |
| Upper heating power supply | 1600W | |
| Lower heating power supply | 1600W | |
| IR heating power supply | 5000W(2000W controlled) | |
| Power supply | 220V, 50/60Hz | |
| Maximum | 680*550mm | |
| Minimum | 10*10mm | |
| Temperature measuring interfaces | 5pcs | |

| Chip zoom in and zoom out | 2-50/times | |
|---------------------------------|-------------------|--|
| The PCB thickness | 0.5 8mm | |
| Apply chip size | 0.8*0.8 120*120mm | |
| Applicable minimum chip spacing | 0.15mm | |
| Maximum mouting load | 300g | |
| Mounting precision | ±0.01mm | |
| Machine dimension | L970*W700*H830mm | |
| Machine weight | 200KG | |



Shenzhen Wisdomshow Technology Co.,ltd







b bgaxraymachine.com

No.6, Haosi Western Industry, Shangjing Town, Bao'an District, Shenzhen, China